

JPW
\$



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Cobbley et al.

Serial No.: 10/693,286

Filed: October 23, 2003

For: METHOD FOR MANUFACTURING
FLIP-CHIP SEMICONDUCTOR
ASSEMBLY

Confirmation No.: 2348

Examiner: T. Nguyen

Group Art Unit: 2813

Attorney Docket No.: 2269-3437.7US
(97-0514.07/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 27, 2005
Date

Rachael M. Harris
Signature

Rachael M. Harris
Name (Type/Print)

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 be considered by the Examiner and made of record. Copies of U.S. patents and U.S. patent publications are not being submitted pursuant to M.P.E.P. 609 III A(2). Copies of foreign patent documents and non-patent literature are enclosed pursuant to 37 C.F.R. § 1.98(a)(2). The listed documents

were cited by the Office in co-pending application Serial No. 10/900,776, filed on July 27, 2004, and directed to a related invention.

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
US - 6,720,574	04/2004	Arnold et al.

Applicants offer to supply any explanation or discussion of the document which the Examiner feels is necessary or desirable and which is requested.

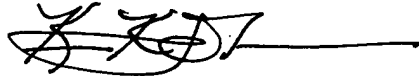
This Supplemental Information Disclosure Statement is filed after the mailing date of the final Office Action under 37 C.F.R. § 1.113, but before payment of the issue fee.

I hereby certify that no item of information contained in the Supplemental Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the statement. Pursuant to 37 C.F.R. § 1.97(d)(ii), applicant hereby requests consideration of the accompanying Supplemental Information Disclosure Statement. The fee

Serial No. 10/693,286

pursuant to 37 C.F.R. §1.17(p) for consideration of this Supplemental Information Disclosure Statement is enclosed.

Respectfully submitted,



Kevin K. Johanson
Registration No. 38,506
Attorney for Applicants
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: January 25, 2005

KKJ/dlm:rmh

Enclosures: Form PTO-1449 or PTO/SB/08

Check No. 7312 in the amount of \$180.00

Document in ProLaw

PTO/SB/08A (10-01)